3.3V CMOS 16-BIT BUFFER/LINE DRIVER

IDT74FCT163244A/C

FEATURES:

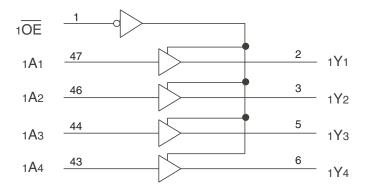
- 0.5 MICRON CMOS Technology
- Typical tsk(o) (Output Skew) < 250ps
- ESD > 2000V per MIL-STD-883, Method 3015; > 200V using machine model (C = 200pF, R = 0)
- Vcc = 3.3V ± 0.3V, Normal Range, or Vcc = 2.7V to 3.6V, Extended Range
- CMOS power levels (0.4 w typ. static)
- · Rail-to-rail output swing for increased noise margin
- Low Ground Bounce (0.3V typ.)
- Inputs (except I/O) can be driven by 3.3V or 5V components
- · Available in SSOP, TSSOP, and TVSOP packages

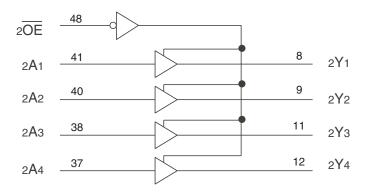
DESCRIPTION:

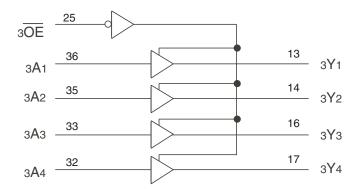
The FCT163244 16-bit buffer/line drivers are built using advanced dual metal CMOS technology. These high-speed, low-power devices offer bus/backplane interface capability with improved packing density. These devices have a flow-through organization for simplifying board layout. The three-state controls operate these devices in a Quad-Nibble, Dual-Byte or single 16-bit word mode. All inputs are designed with hysteresis for improved noise margin.

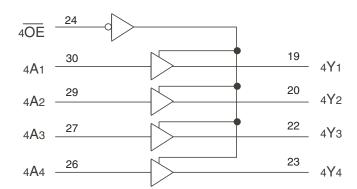
The inputs of the FCT163244 can be driven from either 3.3V or 5V devices. This feature allows the use of these devices as translators in a mixed 3.3V/5V supply system. Thus, the FCT163244 can be used as buffers to connect 5V components to a 3.3V bus.

FUNCTIONAL BLOCK DIAGRAM







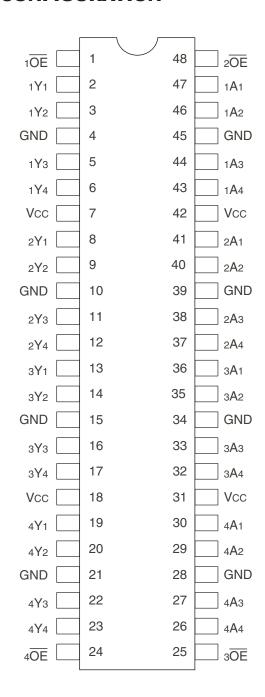


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INDUSTRIAL TEMPERATURE RANGE

SEPTEMBER 2009

PIN CONFIGURATION



SSOP/ TSSOP/ TVSOP TOP VIEW

ABSOLUTE MAXIMUM RATINGS(1)

Symbol	Description	Max	Unit
VTERM ⁽²⁾	Terminal Voltage with Respect to GND	-0.5 to +4.6	V
VTERM ⁽³⁾	Terminal Voltage with Respect to GND	-0.5 to 7	V
VTERM ⁽⁴⁾	Terminal Voltage with Respect to GND	-0.5 to Vcc+0.5	V
Tstg	Storage Temperature	-65 to +150	°C
Іоит	DC Output Current	-60 to +60	mA

NOTES:

- 1. Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
- 2. Vcc terminals.
- 3. Input terminals.
- 4. Outputs and I/O terminals.

CAPACITANCE (TA = +25°C, F = 1.0MHz)

	Symbol	Parameter ⁽¹⁾	Conditions	Тур.	Max.	Unit
	CIN	Input Capacitance	VIN = 0V	3.5	6	pF
ſ	Соит	Output Capacitance	Vout = 0V	3.5	8	pF

NOTE:

1. This parameter is measured at characterization but not tested.

PIN DESCRIPTION

Pin Names	Description		
x OE 3-State Output Enable Inputs (Active LOW)			
x A x Data Inputs			
хҮх	3-State Outputs		

FUNCTION TABLE(1)

Inp	Outputs	
х ОЕ	хАх	хҮх
L	L	L
L	Н	Н
Н	Х	Z

NOTE:

- 1. H = HIGH Voltage Level
 - X = Don't Care
 - L = LOW Voltage Level
 - Z = High-Impedance

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

 $Following\ Conditions\ Apply\ Unless\ Otherwise\ Specified:$

Industrial: $TA = -40^{\circ}C$ to $+85^{\circ}C$, VCC = 2.7V to 3.6V

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Typ. ⁽²⁾	Max.	Unit
ViH	Input HIGH Level (Input pins)	Guaranteed Logic HIGH Level		2	_	5.5	V
	Input HIGH Level (I/O pins)			2	_	Vcc+0.5	
VIL	Input LOW Level (Input and I/O pins)	Guaranteed Logic LOW Level		-0.5	_	0.8	V
Іін	Input HIGH Current (Input pins)	Vcc = Max.	VI = 5.5V	_	_	±1	
	Input HIGH Current (I/O pins)		VI = VCC	_	_	±1	μΑ
lıL	Input LOW Current (Input pins)		VI = GND	_	_	±1	
	Input LOW Current (I/O pins)		VI = GND	_	_	±1	
lozн	High Impedance Output Current	Vcc = Max.	Vo = Vcc	_	_	±1	μA
lozl	(3-State Output pins)		Vo = GND	_	_	±1	
Vik	Clamp Diode Voltage	VCC = Min., IIN = -18mA		_	-0.7	-1.2	V
lodн	Output HIGH Current	VCC = 3.3V, VIN = VIH or VIL, VO = 1.5V(3)		-36	-60	-110	mA
lodl	Output LOW Current	VCC = 3.3V, VIN = VIH or VIL, VO = 1.5V ⁽³⁾		50	90	200	mA
Vон	Output HIGH Voltage	Vcc = Min.	Iон = -0.1mA	Vcc-0.2	_	_	
		VIN = VIH or VIL	Iон = -3mA	2.4	3	_	V
		Vcc = 3V	IOH = -8mA	2.4(5)	3	_	
		VIN = VIH or VIL					
Vol	Output LOW Voltage	Vcc = Min.	IoL = 0.1mA	_	_	0.2	
		VIN = VIH or VIL	IoL = 16mA	_	0.2	0.4	
			IOL = 24mA	_	0.3	0.55	V
		VCC = 3V	IOL = 24mA	_	0.3	0.5	
		VIN = VIH or VIL					
los	Short Circuit Current ⁽⁴⁾	Vcc = Max., Vo = GND ⁽³⁾		-60	-135	-240	mA
VH	Input Hysteresis	_		_	150	_	mV
ICCL ICCH ICCZ	Quiescent Power Supply Current	Vcc = Max. Vin = GND or Vcc		_	0.1	10	μА

NOTES:

- 1. For conditions shown as Min. or Max., use appropriate value specified under Electrical Characteristics for the applicable device type.
- 2. Typical values are at Vcc = 3.3V, +25°C ambient.
- 3. Not more than one output should be shorted at one time. Duration of the test should not exceed one second.
- 4. This parameter is guaranteed but not tested.
- 5. VoH = Vcc-0.6V at rated current.

POWER SUPPLY CHARACTERISTICS

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Тур.(2)	Max.	Unit
Δlcc	Quiescent Power Supply Current TTL Inputs HIGH	Vcc = Max. Vin = Vcc - 0.6V ⁽³⁾		_	2	30	μА
ICCD	Dynamic Power Supply Current ⁽⁴⁾	Vcc = Max. Outputs Open xOE = GND One Input Togging 50% Duty Cycle	VIN = VCC VIN = GND		50	75	μΑ/ MHz
Ic	Total Power Supply Current ⁽⁶⁾	Vcc = Max. Outputs Open fi = 10MHz	VIN = VCC VIN = GND		0.5	0.8	mA
		50% Duty Cycle xOE = GND One Bit Toggling	VIN = VCC - 0.6V VIN = GND	_	0.5	0.8	
		Vcc = Max. Outputs Open fi = 2.5MHz 50% Duty Cycle	VIN = VCC VIN = GND	_	2	3(5)	
		xOE = GND Sixteen BitsTogging	VIN = VCC - 0.6V VIN = GND	_	2	3.3(5)	

NOTES:

- 1. For conditions shown as Min. or Max., use appropriate value specified under Electrical Characteristics for the applicable device type.
- 2. Typical values are at Vcc = 3.3V, +25°C ambient.
- 3. Per TTL driven input. All other inputs at Vcc or GND.
- 4. This parameter is not directly testable, but is derived for use in Total Power Supply Calculations.
- 5. Values for these conditions are examples of the lcc formula. These limits are guaranteed but not tested.
- 6. IC = IQUIESCENT + INPUTS + IDYNAMIC
 - $IC = ICC + \Delta ICC DHNT + ICCD (fcpNcp/2 + fiNi)$
 - Icc = Quiescent Current (IccL, IccH and Iccz)
 - ΔIcc = Power Supply Current for a TTL High Input
 - DH = Duty Cycle for TTL Inputs High
 - NT = Number of TTL Inputs at DH
 - ICCD = Dynamic Current caused by an Input Transition Pair (HLH or LHL)
 - fcP = Clock Frequency for Register Devices (Zero for Non-Register Devices)
 - NCP = Number of Clock Inputs at fcP
 - fi = Input Frequency
 - Ni = Number of Inputs at fi

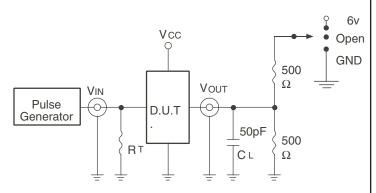
SWITCHING CHARACTERISTICS OVER OPERATING RANGE(1)

			FCT163244A		FCT163224C		
Symbol	Parameter	Condition ⁽²⁾	Min. ⁽³⁾	Max.	Min. ⁽³⁾	Max.	Unit
tPLH	Propagation Delay	CL = 50pF	1.5	4.8	1.5	4.1	ns
tPHL	xAx to xYx	$RL = 500\Omega$					
tpzh	Output Enable Time		1.5	6.2	1.5	5.8	ns
tPZL							
tphz	Output Disable Time		1.5	5.6	1.5	5.2	ns
tPLZ							
tsk(o)	Output Skew ⁽⁴⁾		_	0.5	_	0.5	ns

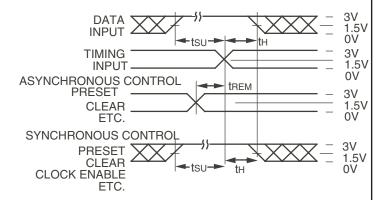
NOTES:

- 1. Propagation Delays and Enable/Disable times are with Vcc = 3.3V±0.3V (normal range). For Vcc = 2.7 to 3.6V (extended range), all Propagation Delays and Enable/Disable times should be degraded by 20%.
- 2. See test circuit and waveforms.
- 3. Minimum limits are guaranteed but not tested on Propagation Delays.
- 4. Skew between any two outputs of the same package switching in the same direction. This parameter is guaranteed by design.

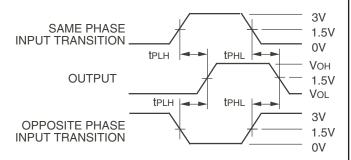
TEST CIRCUITS AND WAVEFORMS



Test Circuits for All Outputs



Set-up, Hold, and Release Times



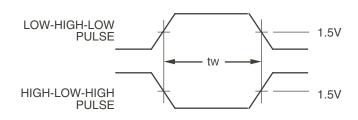
Propagation Delay

SWITCH POSITION

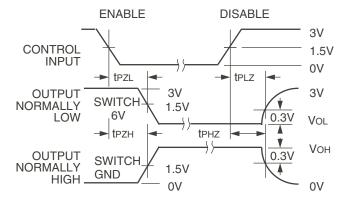
Test	Switch
Open Drain Disable Low Enable Low	6V
Disable High Enable High	GND
All Other Tests	Open

DEFINITIONS:

- CL = Load capacitance: includes jig and probe capacitance.
- RT = Termination resistance: should be equal to ZouT of the Pulse Generator.



Pulse Width

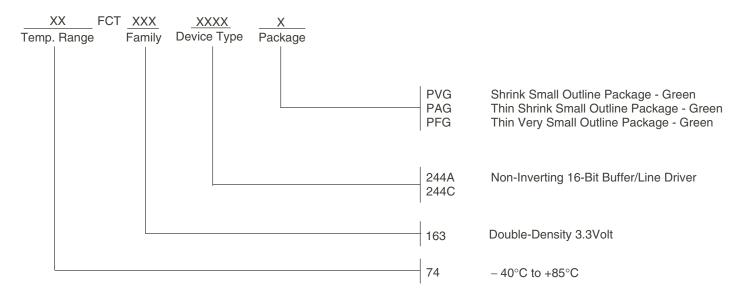


Enable and Disable Times

NOTES:

- 1. Diagram shown for input Control Enable-LOW and input Control Disable-HIGH.
- 2. Pulse Generator for All Pulses: Rate \leq 1.0MHz; tr \leq 2.5ns; tr \leq 2.5ns.
- 3. if Vcc is below 3V, input voltage swings should be adjusted not to exceed Vcc.

ORDERING INFORMATION



Datasheet Document History

09/10/09 Pg.6 Updated the ordering information by removing the "IDT" notation and non RoHS part.

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